

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (mA)	Q_g (Typ.)
20	0.396 at $V_{GS} = 4.5$ V	600	0.75
	0.456 at $V_{GS} = 2.5$ V	500	
	0.546 at $V_{GS} = 1.8$ V	350	
	1.100 at $V_{GS} = 1.5$ V	50	

FEATURES

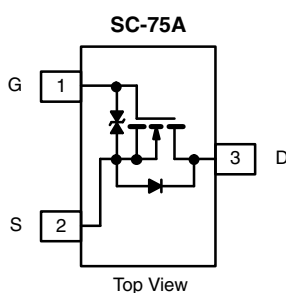
- TrenchFET® Power MOSFET: 1.2 V Rated
- 100 % R_g Tested
- Gate-Source ESD Protected: 1000 V
- Material categorization:
For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits



Ordering Information:
Si1012CR-T1-GE3 (Lead (Pb)-free and Halogen-free)

Marking Code: K

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	$T_A = 25$ °C 0.63 ^{a, b}	A
		$T_A = 70$ °C 0.5 ^{a, b}	
Pulsed Drain Current ($t = 300$ μ s)	I_{DM}	2	
Continuous Source-Drain Diode Current	I_S	0.2 ^{a, b}	A
Maximum Power Dissipation ^a	P_D	$T_A = 25$ °C 0.24 ^{a, b}	W
		$T_A = 70$ °C 0.15 ^{a, b}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	R_{thJA}	$t \leq 5$ s 440	530	°C/W
		Steady State 540	650	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. $t = 5$ s.

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	20			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		17		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 1.8		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	0.4		1	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 30	μA
		V _{DS} = 0 V, V _{GS} = ± 4.5 V			± 1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 85 °C			10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = ≥ 5 V, V _{GS} = 4.5 V	2			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 0.6 A		0.330	0.396	Ω
		V _{GS} = 2.5 V, I _D = 0.3 A		0.380	0.456	
		V _{GS} = 1.8 V, I _D = 0.3 A		0.420	0.546	
		V _{GS} = 1.5 V, I _D = 0.05 A		0.720	1.100	
Forward Transconductance	g _{fs}	V _{DS} = 10 V, I _D = 0.5 A		7.5		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		43		pF
Output Capacitance	C _{oss}			14		
Reverse Transfer Capacitance	C _{rss}			8		
Total Gate Charge	Q _g	V _{DS} = 10 V, V _{GS} = 8 V, I _D = 0.6 A		1.3	2	nC
		V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 0.6 A		0.75	1.2	
Q _{gs}			0.15			
Q _{gd}			0.13			
Gate Resistance	R _g	f = 1 MHz	2.4	12.2	24.4	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 10 V, R _L = 20 Ω I _D ≅ 0.5 A, V _{GEN} = 4.5 V, R _g = 1 Ω		11	20	ns
Rise Time	t _r			16	24	
Turn-Off Delay Time	t _{d(off)}			26	39	
Fall Time	t _f			11	20	
Drain-Source Body Diode Characteristics						
Pulse Diode Forward Current ^a	I _{SM}				2	A
Body Diode Voltage	V _{SD}	I _S = 0.5 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 0.5 A, dI/dt = 100 A/μs		10	15	ns
Body Diode Reverse Recovery Charge	Q _{rr}			2	4	nC
Reverse Recovery Fall Time	t _a			5		ns
Reverse Recovery Rise Time	t _b			5		

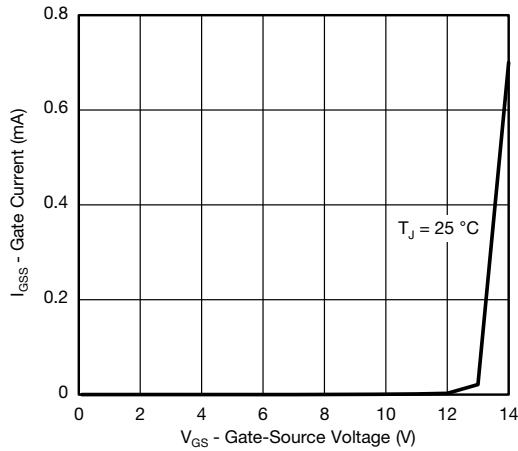
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

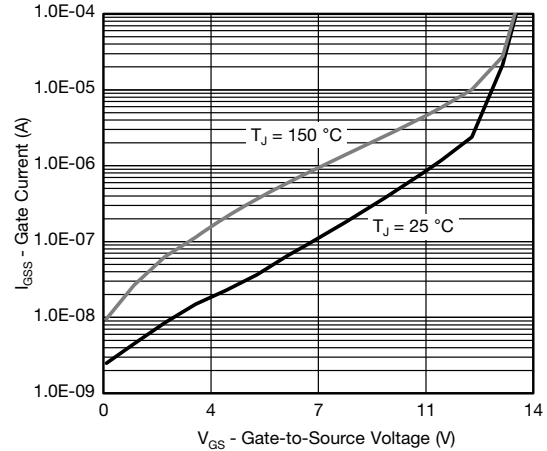
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

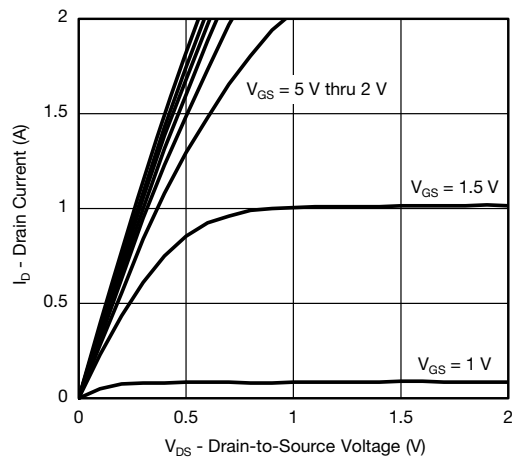
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



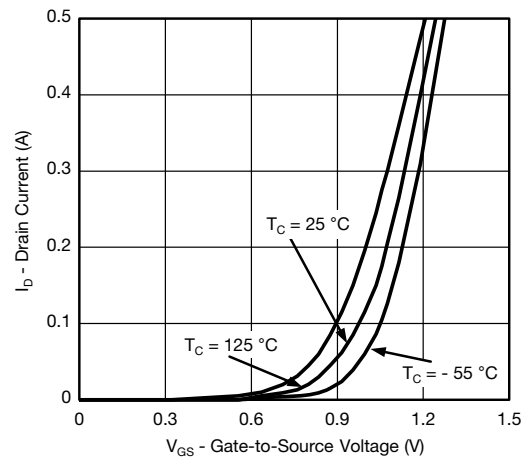
Gate Current vs. Gate-Source Voltage



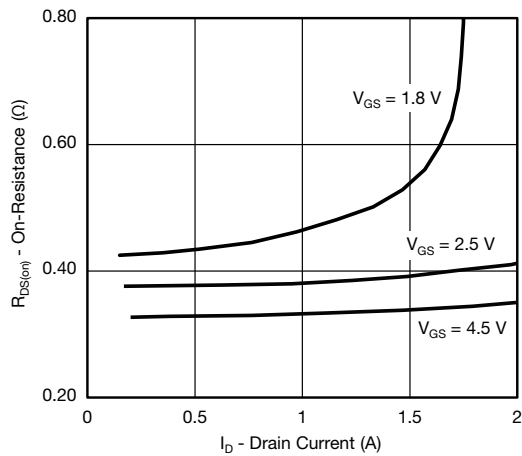
Gate Current vs. Gate-Source Voltage



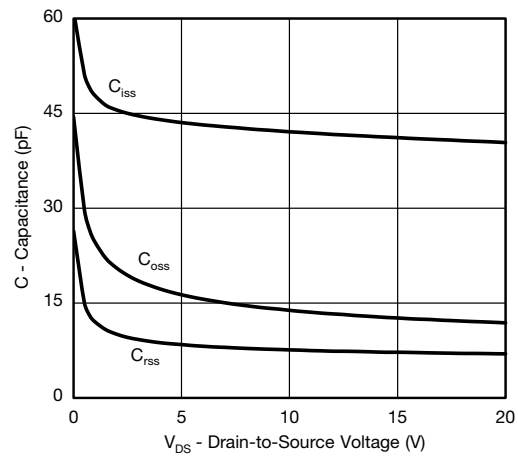
Output Characteristics



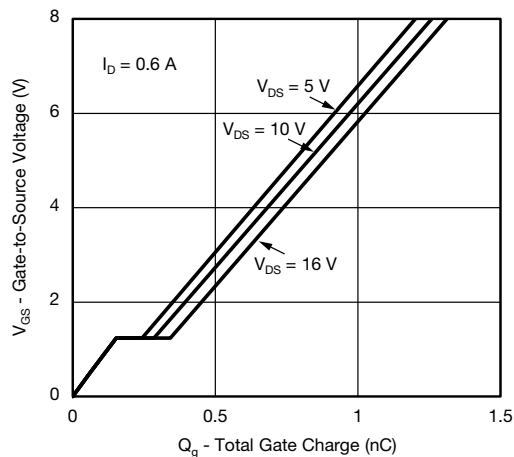
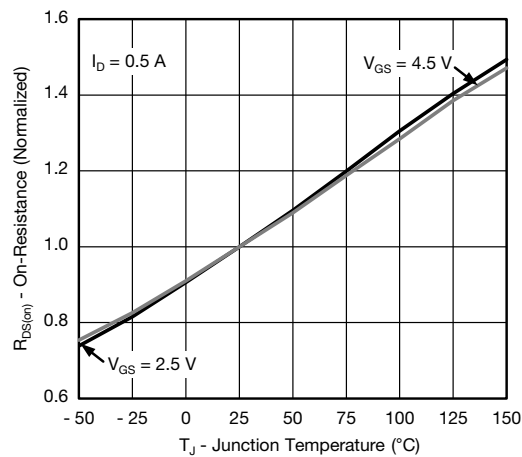
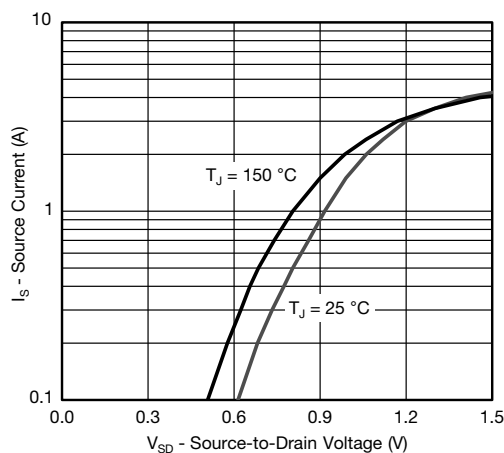
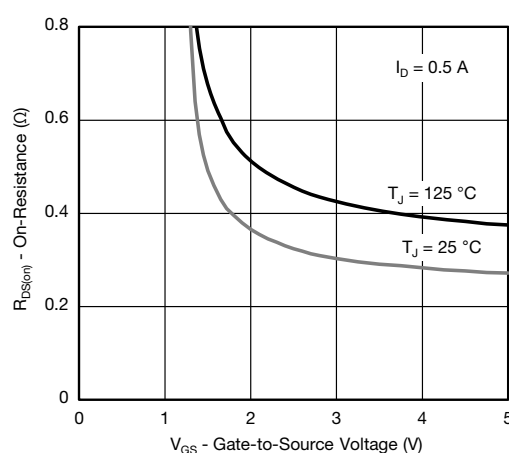
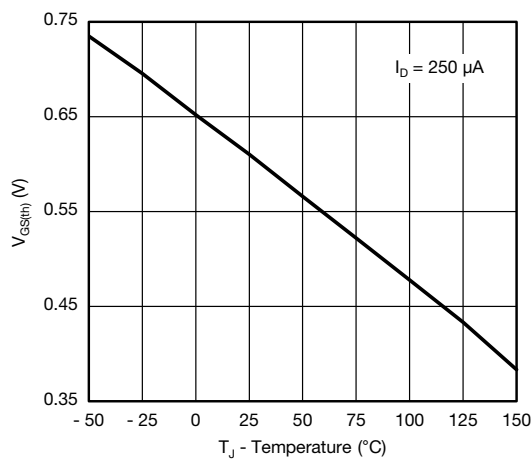
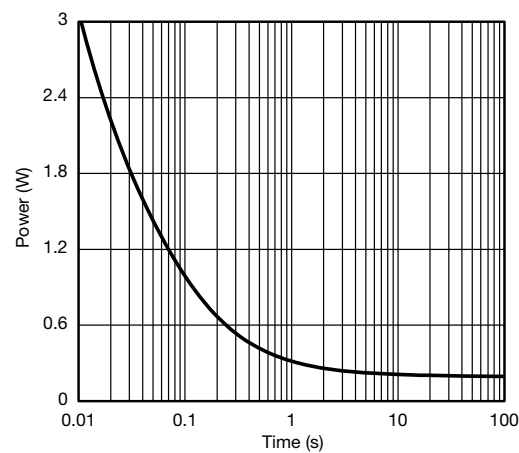
Transfer Characteristics



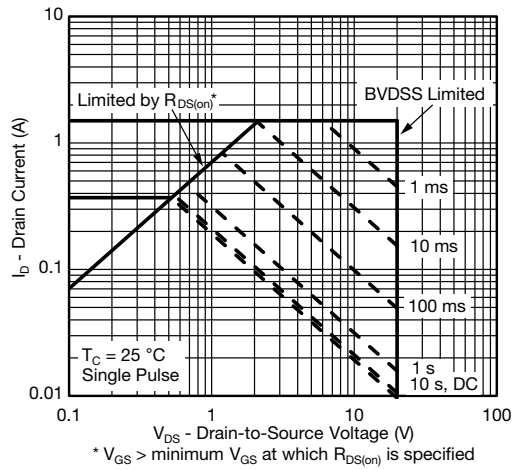
On-Resistance vs. Drain Current



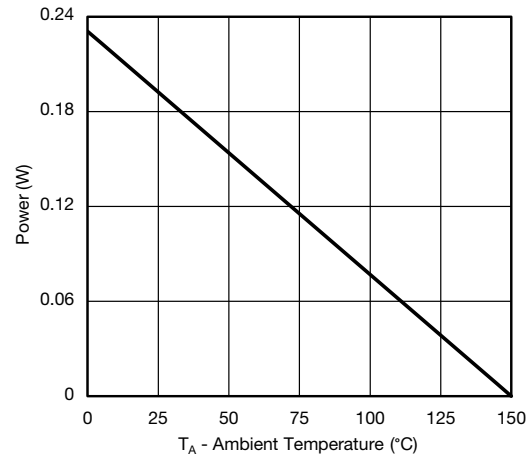
Capacitance

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)**Gate Charge****On-Resistance vs. Junction Temperature****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power, Junction-to-Ambient**

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

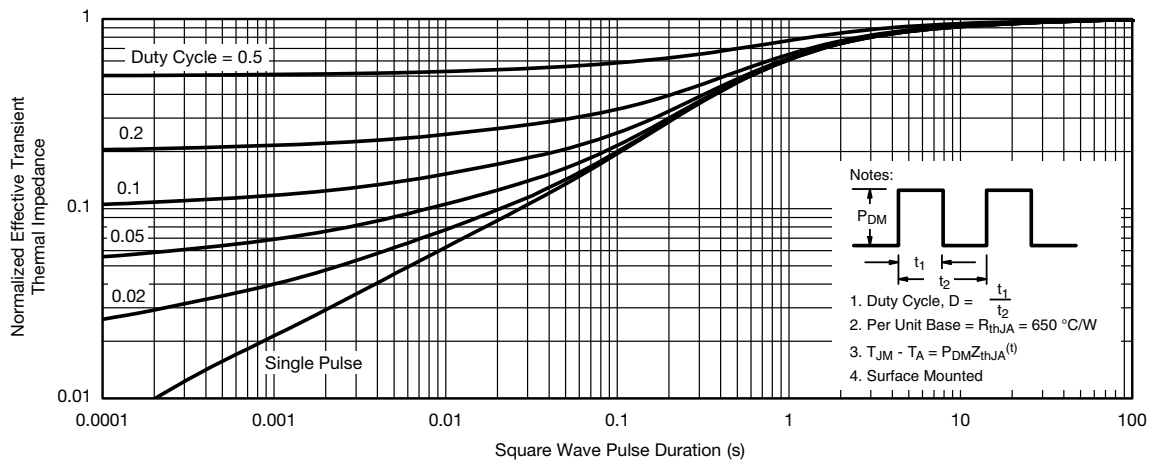


Safe Operating Area, Junction-to-Ambient



Power Derating, Junction-to-Ambient

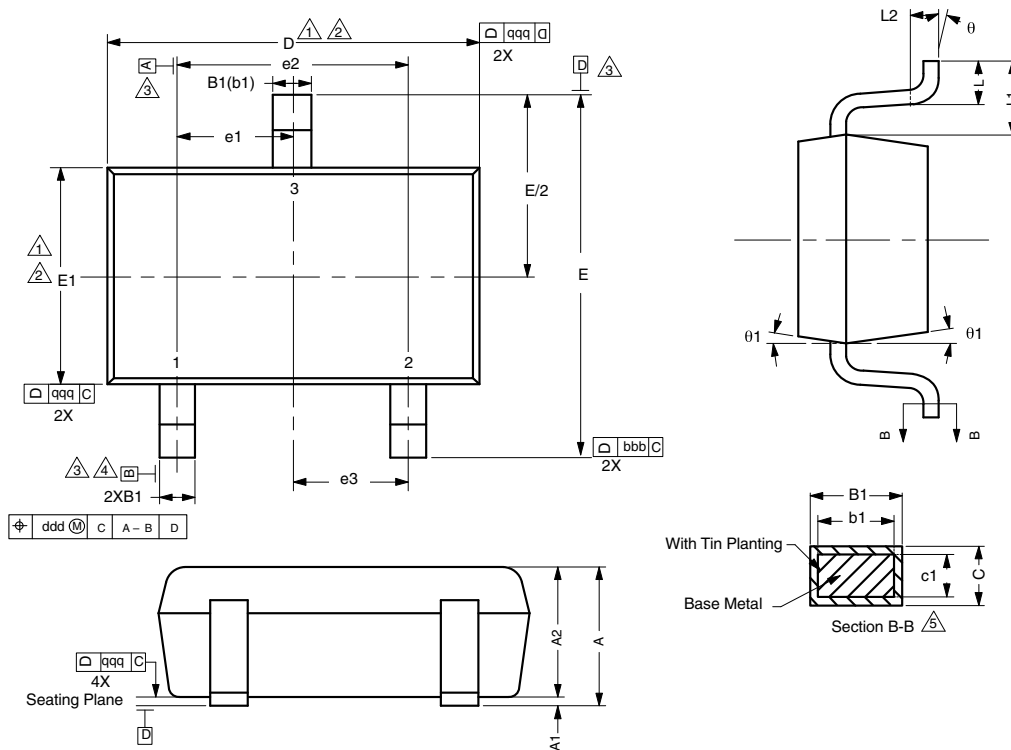
* The power dissipation P_D is based on $T_{J(max)} = 150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67519.

SC-75A: 3 Leads



DWG: 5868

Notes

Dimensions in millimeters will govern.

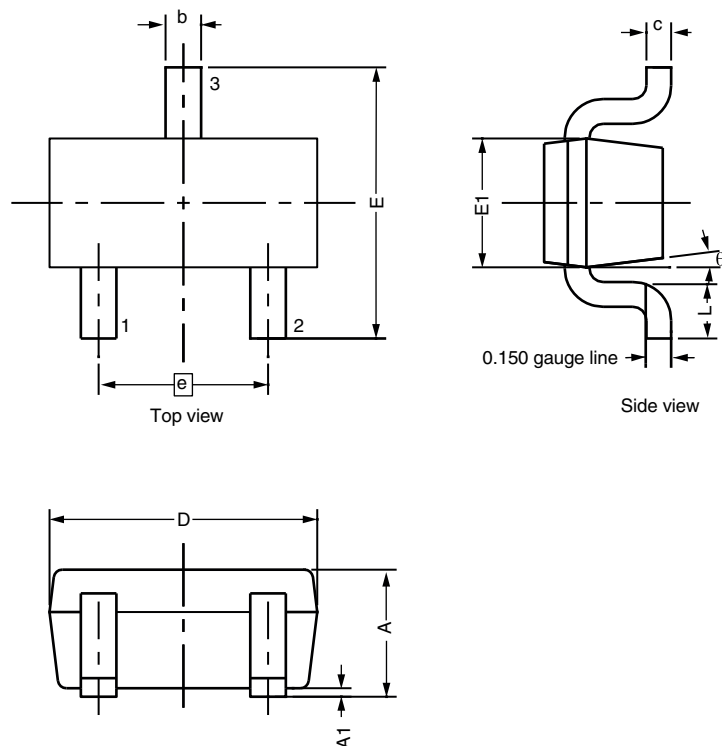
1. Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.
2. Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
3. Datums A, B and D to be determined 0.10 mm from the lead tip.
4. Terminal positions are shown for reference only.
5. These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES
aaa	0.10
bbb	0.10
ccc	0.10
ddd	0.10

DIM.	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	-	-	0.80	
A ₁	0.00	-	0.10	
A ₂	0.65	0.70	0.80	
B ₁	0.19	-	0.24	5
b ₁	0.17	-	0.21	
c	0.13	-	0.15	5
c ₁	0.10	-	0.12	5
D	1.48	1.575	1.68	1, 2
E	1.50	1.60	1.70	
E ₁	0.66	0.76	0.86	1, 2
e ₁	0.50 BSC			
e ₂	1.00 BSC			
e ₃	0.50 BSC			
L	0.15	0.205	0.30	
L ₁	0.40 ref.			
L ₂	0.15 BSC			
θ	0°	-	8°	
θ ₁	4°	-	10°	



For Samsung only

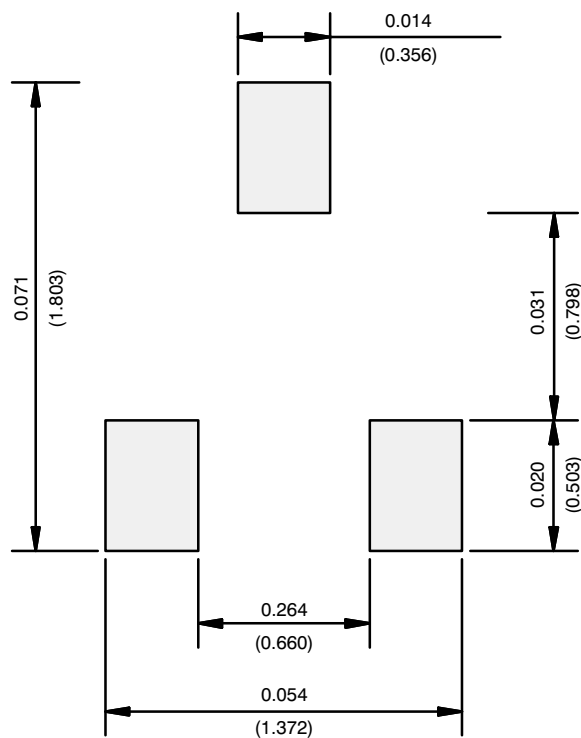


Notes

- (1) Millimeters will govern.
- (2) Dimension exclusive of mold gate burrs.
- (3) Dimension exclusive of mold flash and cutting burrs.

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.60	0.70	0.80	0.024	0.028	0.031
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.18	0.22	0.32	0.007	0.009	0.013
c	0.11	0.13	0.21	0.004	0.005	0.008
D	1.48	1.58	1.68	0.058	0.062	0.066
E	1.50	1.60	1.70	0.059	0.063	0.067
E1	0.66	0.76	0.86	0.026	0.030	0.034
e	0.95	1.00	1.05	0.037	0.039	0.041
L	0.22	0.32	0.42	0.009	0.013	0.017
θ	4°	7°	10°	4°	7°	10°

RECOMMENDED MINIMUM PADS FOR SC-75A: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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